

Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

Molex Connector Corporation 0739270004

For any questions, you can email us directly: <u>sales@integrated-circuit.com</u>



Distributor of Molex Connector Corporation: Excellent Integrated System Limited Datasheet of 0739270004 - CONN SFP CAGE R/A SOLDER POST Contact us: sales@integrated-circuit.com Website: www.integrated-circuit.com





MOLEX[®] APPLICATION SPECIFICATION

1.0 SCOPE

This specification covers the **0.80** mm (**.031** inch) centerline Small Form-factor Pluggable (SFP) connector and cage assembly. The following specification covers the use and requirements for these components.

The SFP connector is a 20 circuit surface mount device, with a high temperature thermoplastic housing. It is used to connect SFP optical or copper pluggable transceivers to printed circuit boards (PCBs). Features of the connector include alignment pegs for mounting to the circuit board, and a Pin 1 identifier. The connector is packaged in tape-and-reel for high speed assembly.

The SFP cage is used with the SFP connector for guiding and securing SFP optical or copper pluggable transceivers to PCBs such as motherboards and host adapter cards.

The SFP cage assembly is available as a one-piece kit or as separate components to accommodate various board assembly processes. The cage assembly features EMI spring fingers which provide electrical contact to the card bezel. The cage cover and base incorporate positive mechanical locking latches. The cage base features a locking latch for positive latching of industrycompatible modules. The cage base is available in three versions: standard solder post, PCI solder post (for use with PCI cards), and press-fit post. The base also features three rear pins for EMI suppression to the PCB.

The cage cover is packaged in trays for hand assembly. The cage base is available in trays or tape-and reel.

<u>REVISION:</u>	ECR/ECN INFORMATION: EC No: UCP2015-3716	TITLE: Ap	ILE: Application Specification for Small Form-factor Pluggable (SFP)		SHEET No.	
В	<u>DATE:</u> 2015 / 09 / 09	Connector and Cage Assembly			2 of 0	
DOCUMENT NUMBER:		REVIS	SED BY:	CHECKED BY:	APPROVED BY:	
AS-74441-001		Rober	t Barker	Donald Morgan	Steve Miller	
TEMPLATE FILENAME: APPLICATION SPECISIZE A1(V 2) DOC						



MOLEX[®] APPLICATION SPECIFICATION

2.0 **GENERAL REQUIREMENTS**

2.1 Part numbers

	DESCRIPTION	PA	<u>RT NUMBER</u>		
	Connector (20 circuit)	744	441-0001 7444	41-0010	
		744	441-0021 7444	41-0031	
	One-Piece Press Fit C	age 739	927-0001		
	One-Piece Solder Post	t Cage 739	927-0002		
	One-Piece PCI Cage	739	927-0004		
	Cage Cover	739	927-0020		
	Press-Fit Cage Base	739	927-0030		
	Solder Post Cage Base	e 739	927-0040		
	PCI Cage Base	739	927-0060		
2.2	Connector Documen	tation			
	DESCRIPTION	DC	CUMENT NUMBER		
	Sales drawing	SD	-74441-001		
	Packaging specification	on PK	-70873-1201		
	Product specification	PS	-74441-001		
2.3	Cage Assembly Docu	imentation			
	DESCRIPTION	DC	CUMENT NUMBER		
	Sales Drawings:				
	SFP Cage Assembly				
	Press-fit Version	SD	-73927-001		
	SFP Cage Assembly				
	Solder Post Version	SD	-73927-002		
	SFP Cage Assembly				
	PCI Version	SD	-73927-004		
	Packaging Specification	on No	t Available		
	Product Specification	No	t Available		
		I			
REVISION:	ECR/ECN INFORMATION:	<u>TITLE:</u> Application Sp	pecification for		SHEET No.
R	EC No: UCP2015-3716	Small Form-fa	ctor Pluggable (SFI	P)	3 of 6
	<u>DATE:</u> 2015 / 09 / 09	Connector and	l Cage Assembly		
DOCUMENT	NUMBER:	REVISED BY:	CHECKED BY:	APPROV	ED BY:
<u>A</u> S	S-74441-001	Robert Barker	Donald Morgan	Steve	Miller
			TEMPLATE FILENAME	: APPLICATION_SPEC	SIZE_A](V.2).DOC



MOLEX[®] APPLICATION SPECIFICATION

2.4 Packaging

The Molex SFP connector is supplied on tape and reel packaging for high speed assembly. One piece cage kits are supplied in trays of 24 per tray. If ordered separately, the cage cover and base are supplied in trays of 24 or on tape-and-reel.

2.5 Board Thickness

There is no required board thickness for single-sided printed circuit boards mounting. For double-sided printed circuit board mounting, PC board to be a minimum of 3.0 mm (.118 Inch) thick.

2.6 Board Layout

The board layout must conform to the Small Form-factor Pluggable (SFP) MSA agreement. See the aforementioned sales drawings for the required board layout.

3.0 ASSEMBLY

3.1 Connector Assembly

3.1.1 Connector Alignment

The Molex SFP connector shall be placed on the host printed circuit board using the aligning posts. The terminals shall be lined up on the circuit board in such a way that the solder feet shall be placed over the solder pads on the host board.

REVISION:	ECR/ECN INFORMATION:	TITLE: Application Specification for			SHEET No.
В	EC No: UCP2015-3716	Small Form-factor Pluggable (SFP)			4 of 6
	<u>DATE:</u> 2015 / 09 / 09	Connector and			
DOCUMENT NUMBER:		REVISED BY:	CHECKED BY:	APPROVED BY:	
AS-74441-001		Robert Barker	Donald Morgan	Steve Miller	
TEMPLATE FILENAME APPLICATION SPECISIZE AVV 2) DOC					



MOLEX[®] APPLICATION SPECIFICATION

3.1.2 Connector Seating Forces

It is recommended that the connector is seated with the specified force to assure that the terminal tails make sufficient contact with the previously applied solder paste: Connector Seating Force = 130 grams

3.2 Cage Assembly

3.2.1 Cage Registration

The cage base or one-piece cage kit mounting post and EMI suppression pins must be aligned with the matching printed circuit board hole locations.

3.2.2 Seating – Cages with Solder Tails

As the cage base solder posts are for clearance and fit only, the force required for seating the cage is minimal. The bottom of the cage must be seated and soldered so that there is no more than 0.05 mm (.002 Inch) gap between the shoulder of the solder posts and the PCB. The gap between the front of the cage base and the PCB should be no more than 0.1 mm (.004 Inch).

3.2.3 Seating – Cages with Press-Fit Tails

Insertion force is 30 to 35 pounds. Insert with top cage installed.

Use standard "flat rock" insertion equipment.

4.0 SOLDERING REQUIREMENTS

4.1 **Processing requirements**

Peak reflow temperatures should not exceed 245 degrees C.

REVISION:	ECR/ECN INFORMATION:	TITLE: Application Specification for			SHEET No.
В	EC No: UCP2015-3716	Small Form-factor Pluggable (SFP)			5 of 6
	DATE: 2015 / 09 / 09	Connector and	J 01 U		
DOCUMENT NUMBER:		REVISED BY:	CHECKED BY:	APPROVED BY:	
AS-74441-001		Robert Barker	Donald Morgan	Steve Miller	
TEMPLATE FILENAME: APPLICATION_SPEC[SIZE_A](V.2).DOC					



Distributor of Molex Connector Corporation: Excellent Integrated System Limited Datasheet of 0739270004 - CONN SFP CAGE R/A SOLDER POST Contact us: sales@integrated-circuit.com Website: www.integrated-circuit.com

MOLEX[®] APPLICATION SPECIFICATION

4.2 Stencil Requirements

See Figure 1 for a recommended stencil layout.

A minimum solder paste thickness of 0.13 mm (.005 Inch) is recommended.

